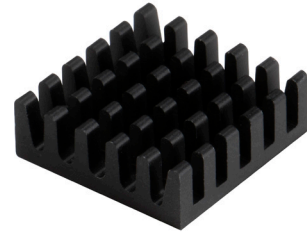


MODEL: HSB04-171706 | **DESCRIPTION:** HEAT SINK**FEATURES**

- BGA design
- small footprint
- aluminum alloy
- black anodized finish

**MODEL**

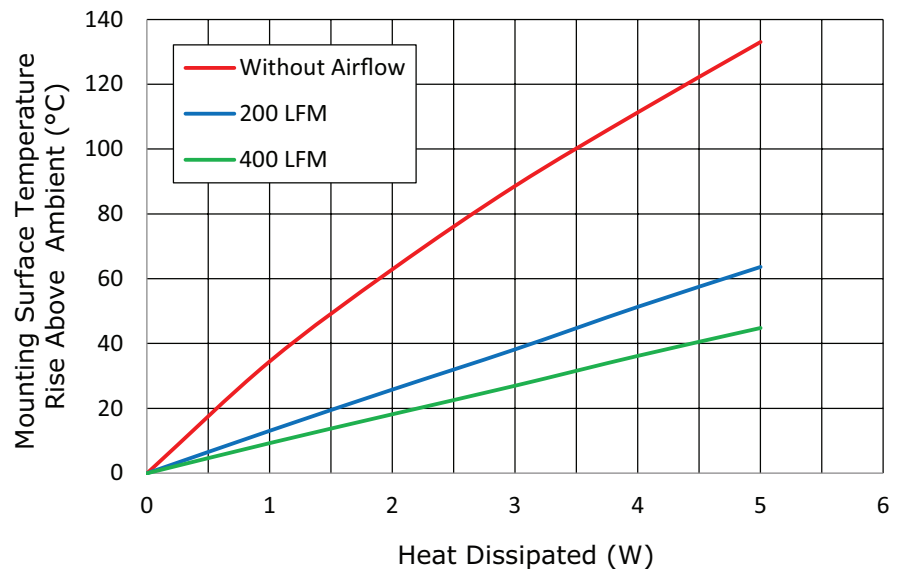
	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT , nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT , nat conv [W]
HSB04-171706	29.73	34.5	13.1	9.3	2.52

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient ($\Delta T = T_{hs} - T_a$) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	34.5	13.1	9.3
2	62.9	25.8	18.2
3	88.6	38.2	27.0
4	111.3	51.3	36.2
5	133.0	63.6	44.8

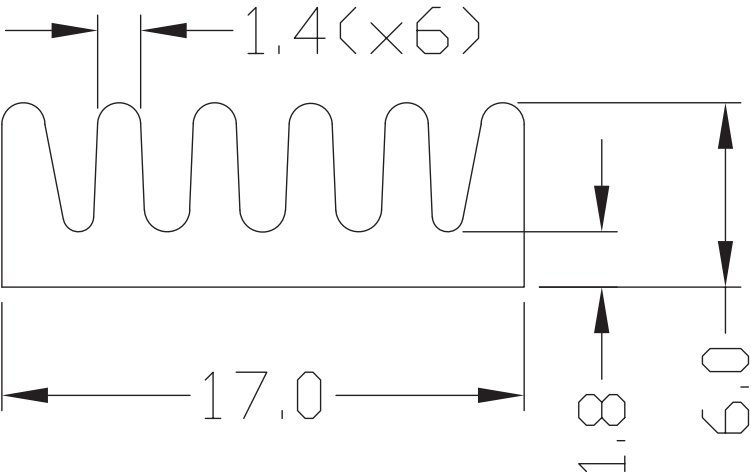
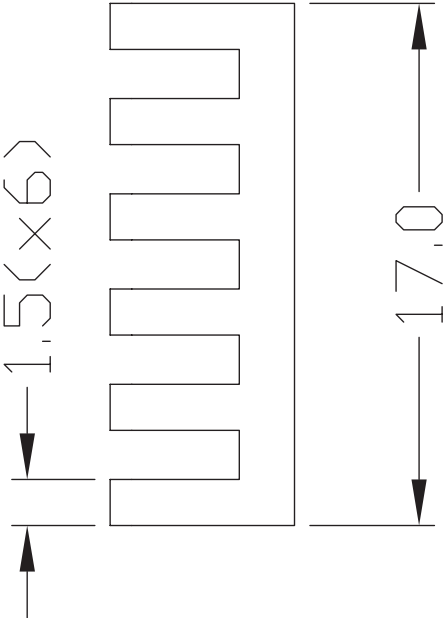
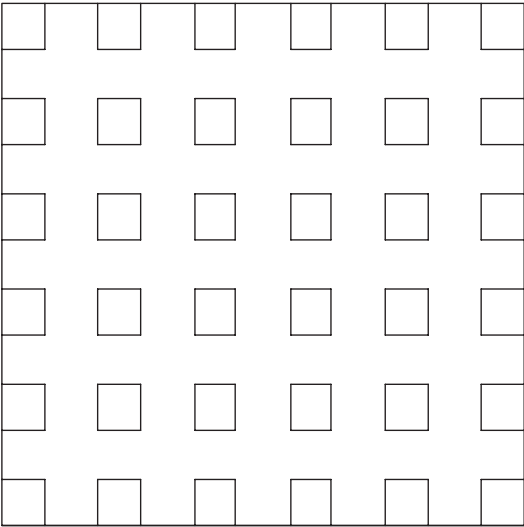
T_{hs} : "hot spot" temperature measured on the heatsink
 T_a : ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	2.7 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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